Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently amended) A method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component comprising:

~~a step of~~ forming a ceramic green sheet on ~~the~~ a surface of a first carrier film including a surface-treated region on which a surface treatment is performed for improving releasability and non-surface-treated regions on which no surface treatment is performed on both sides of the surface-treated region,

~~a step of~~ forming a release layer on ~~the~~ a surface of a second carrier film having a width substantially equal to that of the first carrier film,

~~a step of~~ forming an electrode layer in a predetermined pattern and a spacer layer in a complementary pattern to that of the electrode layer on ~~the~~ a surface of the release layer, thereby forming an inner electrode layer,

~~a step of~~ forming an adhesive layer on ~~the~~ a surface of a third carrier film having a width substantially equal to that of the first carrier film,

~~a step of~~ bringing ~~the~~ a surface of the adhesive layer formed on the third carrier film and ~~the~~ a surface of the ceramic green sheet into close contact with each other and pressing them, thereby bonding the adhesive layer onto the surface of the ceramic green sheet,

~~a step of~~ peeling off the third carrier film from the adhesive layer,

~~a step of~~ pressing and bonding the inner electrode layer formed on the surface of the second carrier film and the ceramic green sheet formed on the surface of the first carrier film onto each other via the adhesive layer, and

~~a step of~~ peeling off the second carrier film from the inner electrode layer, thereby fabricating a multi-layered unit including the ceramic green sheet and the inner electrode layer laminated onto each other,

wherein the adhesive layer is formed by coating the surface of the third carrier film with an adhesive agent solution so that the width of the adhesive layer is:

narrower than the width of the third carrier film by at least 2α, wherein the third carrier film is conveyed by a sheet conveying mechanism and ~~where~~ α is a positive value defined as the maximum width within which one side of a sheet may meander when the sheet is conveyed by the sheet conveying mechanism and is a value inherent to the sheet conveying mechanism,

wider than the width of the ceramic green sheet formed on the surface of the first carrier film and the widths of the release layer and the inner electrode layer formed on the surface of the second carrier film by at least 2α, and

wider than the width of the surface-treated region of the first carrier film by at least 2α.

2. (Original) A method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component in accordance with Claim 1, wherein the ceramic green sheet is formed by coating the surface of the first carrier film with a dielectric paste so that the width of the ceramic green sheet is wider than that of the surface-treated region by at least 2α.

3. (Original) A method for manufacturing a multi-layered for a multi-layered ceramic electronic component in accordance with Claim 2, wherein the inner electrode layer is formed by printing the surface of the second carrier film with an electrode paste and a dielectric paste so that the width of the inner electrode layer is wider than that of the release layer by at least 2α and the ceramic green sheet is formed by coating the surface of the first carrier film with a dielectric paste so that the width of the ceramic green sheet is wider than that of the release layer by at least 2α.

4. (Original) A method for manufacturing a multi-layered for a multi-layered ceramic electronic component in accordance with Claim 3, wherein slit processing is performed on the first carrier film, the ceramic green sheet, the adhesive layer, the inner

electrode layer, the release layer and the third carrier film in the surface-treated region inside of a region on which the release layer is to be formed by coating the surface of the second carrier film with the dielectric paste.

5. (Original) A method for manufacturing a multi-layered for a multi-layered ceramic electronic component in accordance with Claim 1, wherein surface treatment is performed on the surface of the second carrier film for improving the releasability thereof and the release layer is formed on a region on which the surface treatment is performed.

6. (Original) A method for manufacturing a multi-layered for a multi-layered ceramic electronic component in accordance with Claim 2, wherein surface treatment is performed on the surface of the second carrier film for improving the releasability thereof and the release layer is formed on a region on which the surface treatment is performed.

7. (Original) A method for manufacturing a multi-layered for a multi-layered ceramic electronic component in accordance with Claim 3, wherein surface treatment is performed on the surface of the second carrier film for improving the releasability thereof and the release layer is formed on a region on which the surface treatment is performed.

8. (Original) A method for manufacturing a multi-layered for a multi-layered ceramic electronic component in accordance with Claim 4, wherein surface treatment is performed on the surface of the second carrier film for improving the releasability thereof and the release layer is formed on a region on which the surface treatment is performed.

9. (Original) A method for manufacturing a multi-layered for a multi-layered ceramic electronic component in accordance with Claim 1, wherein after the electrode layer was formed on the release layer, the spacer layer is formed on the release layer in a complementary pattern to that of the electrode layer.

10. (Original) A method for manufacturing a multi-layered for a multi-layered ceramic electronic component in accordance with Claim 1, wherein after the spacer layer was formed on the release layer in a complementary pattern to that of the electrode layer to be formed on the release layer, the electrode layer is formed on the release layer.

11. (Original) A method for manufacturing a multi-layered for a multi-layered ceramic electronic component in accordance with Claim 1, wherein the adhesive layer contains dielectric particles having the same composition as that of dielectric particles contained in the ceramic green sheet.

12. (Original) A method for manufacturing a multi-layered for a multi-layered ceramic electronic component in accordance with Claim 1, wherein the adhesive layer contains a binder belonging to the same binder group as that a binder contained in the ceramic green sheet belongs to.

13. (Original) A method for manufacturing a multi-layered for a multi-layered ceramic electronic component in accordance with Claim 1, wherein the spacer layer contains dielectric particles having the same composition as that of dielectric particles contained in the ceramic green sheet.

14. (Original) A method for manufacturing a multi-layered for a multi-layered ceramic electronic component in accordance with Claim 1, wherein the spacer layer contains a binder belonging to the same binder group as that a binder contained in the ceramic green sheet belongs to.

15. (Original) A method for manufacturing a multi-layered for a multi-layered ceramic electronic component in accordance with Claim 1, wherein the adhesive layer is formed so as to have a thickness equal to or thinner than 0.1 μm.

16. (Original) A method for manufacturing a multi-layered for a multi-layered ceramic electronic component in accordance with Claim 1, wherein the ceramic green sheet is formed so as to have a thickness equal to or thinner than 3 μm.

17. (Original) A method for manufacturing a multi-layered for a multi-layered ceramic electronic component in accordance with Claim 1, wherein the ceramic green sheet and the adhesive layer is pressed to each other under a pressure of about 0.2 MPa to about 15 Mpa.